

**Student Forum at the
17th Asia and South Pacific Design Automation Conference (ASP-DAC 2012)
2 February 2012
Sydney Convention Centre, Sydney, Australia
Call for Posters**

**Poster Selection
Committee Chair:**

Oliver Diessel
Uni. of New South Wales, Australia

Committee Members:

Paul Beckett
RMIT, Australia

Ray Cheung
City Uni. of Hong Kong, Hong Kong

Sung Woo Chung
Korea University, Korea

Suhaib Fahmy
Nanyang Tech. Uni., Singapore

Görschwin Fey
University of Bremen, Germany

Yih-Lang Li
National Chiao Tung Uni., Taiwan

Chien-Nan Jimmy Liu
National Central University, Taiwan

Kohei Miyase
Kyushu Institute of Tech., Japan

Shinobu Nagayama
Hiroshima City University, Japan

Masanori Natsui
Tohoku University, Japan

Brian Ng
University of Adelaide, Australia

Elaine Ou
University of Sydney, Australia

Adam Postula
University of Queensland, Australia

Jean-Michel Redouté
Monash University, Australia

Won Woo Ro
Yonsei University, Korea

Partha Roop
Uni. of Auckland, New Zealand

Hiroshi Saito
University of Aizu, Japan

Hayden So
Uni. of Hong Kong, Hong Kong

Chun-Yao Wang
National Tsing Hua Uni., Taiwan

Yu Wang
Tsinghua University, China

Takayuki Watanabe
University of Shizuoka, Japan

Weng-Fai Wong
National Uni. Singapore, Singapore

Shingo Yoshizawa
Hokkaido University, Japan

Evangeline Young
Chinese Uni. of Hong Kong, HK

Xiaomin Zhu
National Uni. Defense Tech., China

The Student Forum at ASP-DAC 2012 is a poster session for graduate students to present their research work. This is a great opportunity for students to get feedback and have discussions with people from academia and industry. Awards will be given for outstanding presentations. Please check the website for updates.

URL:

http://www.aspdac.com/aspdac2012/student_forum/index.html

Eligibility:

Graduate students are eligible for the Student Forum.

Important Dates:

Submission Deadline	4 November 2011
Notification Date	2 December 2011
Forum Date	2 February 2012

Submission Requirements:

1. Abstract of the poster presentation including name, advisor, institution, contact information, estimated graduation date, track number, figures, tables and bibliography (if applicable). The abstract must be no more than two pages long (hard limit).
2. A list of all papers related to the poster presentation authored or co-authored by the student, including posters in Ph.D. Forums at DAC or DATE and the ASP-DAC Student Forum.
3. A published supporting paper authored or co-authored by the student and related to the poster presentation, if available.

Please send the above as a single PDF file to the following address:
aspdac12.sf@cse.unsw.edu.au

Please Note:

- Abstracts of completed research as well as research in early stages can be submitted.
- Submitted abstracts will be reviewed by the poster selection committee. In addition to usual paper selection criteria the following points will be considered in the review process:
 - (1) Methodology and progress towards completed (or almost completed) research.
 - (2) Directions and potential for research at an early stage.
- The poster selection committee will give priority to abstracts meeting the following criteria:
 - (1) Achievements and methodologies that are supported by experimental results.
 - (2) Directions and research potential that are supported by feasibility studies.
 - (3) Work not previously presented at the Ph.D. Forums of DAC or DATE or the ASP-DAC Student Forum.
- The abstract must be in PDF format. The font should be no smaller than 10 points. Please ensure all pages print clearly.
- The abstract must be well organized and should aim to be free of errors.
- The bibliography and the list of published papers must be in IEEE style (See http://www.ieee.org/publications_standards/publications/authors/authors_journals.html).

***Student Forum at the
17th Asia and South Pacific Design Automation Conference (ASP-DAC 2012)
2 February 2012
Sydney Convention Centre, Sydney, Australia***

Tracks:

- [1] **System-Level Modeling and Simulation/Verification**
System-level modeling, specification, language, performance analysis, system-level simulation/verification, hardware-software co-simulation/co-verification, etc.
- [2] **System-Level Synthesis and Optimization:**
System-on-chip and multi-processor SoC (MPSoC) design methodology, hardware-software partitioning, hardware-software co-design, IP/platform-based design, application-specific instruction-set processor (ASIP) synthesis, low power system design, etc.
- [3] **System-Level Memory/Communication Design and Networks on Chip:**
Communication-based architecture design, network-on-chip (NoC) design methodologies and CAD, interface synthesis, system communication architecture, memory architecture, low power communication design, etc.
- [4] **Embedded and Real-Time Systems:**
Embedded system design, real-time system design, OS, middleware, compilation techniques, memory/cache optimization, interfacing and software issues.
- [5] **High-Level/Behavioral/Logic Synthesis and Optimization:**
High-Level/behavioral/RTL synthesis, technology-independent optimization, technology mapping, interaction between logic design and layout, sequential and asynchronous logic synthesis, resource scheduling, allocation, and synthesis.
- [6] **Validation and Verification for Behavioral/Logic Design:**
Logic simulation, symbolic simulation, formal verification, equivalence checking, transaction-level/RTL and gate-level modeling and validation, assertion-based verification, coverage-analysis, constrained-random testbench generation.
- [7] **Physical Design:**
Floorplanning, partitioning, placement, buffer insertion, routing, interconnect planning, clock network synthesis, post-placement optimization, layout verification, package/PCB routing, etc.
- [8] **Timing, Power, Thermal Analysis and Optimization:**
Deterministic and statistical static timing analysis, statistical performance analysis and optimization, low power design, power and leakage analysis, power/ground and package analysis and optimization, thermal analysis, etc.
- [9] **Signal/Power Integrity, Interconnect/Device/Circuit Modeling and Simulation:**
Signal/power integrity, clock and bus analysis, interconnect and substrate modeling/extraction, package modeling, device modeling/simulation, circuit simulation, high-frequency and electromagnetic simulation of circuits, etc.
- [10] **Design for Manufacturability/Yield and Statistical Design:**
DFM, DFY, CAD support for OPC and RET, variability analysis, yield analysis and optimization, reliability analysis, design for resilience and robustness, cell library design, design fabrics, etc.
- [11] **Test and Design for Testability:**
Testable design, fault modeling, ATPG, BIST and DFT, memory test and repair, core and system test, delay test, analog and mixed signal test.
- [12] **Analog, RF and Mixed Signal Design and CAD:**
Analog/RF synthesis, analog layout, verification and simulation techniques, noise analysis, mixed-signal design considerations.
- [13] **Emerging Technologies and Applications:**
- (i) Design case studies for emerging applications: multimedia, consumer electronics, communication, networking, ubiquitous computing and biomedical applications, etc.
 - (ii) Post CMOS technologies: nanotechnology, quantum, optical interconnect, 3D integration, probabilistic architecture, microfluidics, molecular, bioelectronics, etc., with emphasis on modeling, analysis, novel circuit/architecture, CAD tools, and design methodologies.

Sponsored by:
To be confirmed

Supported by:
To be confirmed

Contact Information:
If you have any questions, please e-mail:
aspdac12.sf@cse.unsw.edu.au